

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5743218

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SATOSHI INOUE	09/08/2017
TATSUYA SHIMODA	09/06/2017
KAZUHIRO FUKADA	09/19/2017
KIYOSHI NISHIOKA	06/06/2017
NOBUTAKA FUJIMOTO	09/14/2017
MASAHIRO SUZUKI	09/06/2017

RECEIVING PARTY DATA

Name:	JAPAN ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY
Street Address:	1-1 ASAHIDAI, NOMI-SHI
City:	ISHIKAWA
State/Country:	JAPAN
Postal Code:	923-1292
Name:	SUMITOMO SEIKA CHEMICALS CO., LTD.
Street Address:	346-1, MIYANISHI, HARIMA-CHO
City:	HYOGO
State/Country:	JAPAN
Postal Code:	675-0145

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16586021

CORRESPONDENCE DATA

Fax Number: (203)972-7627

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 203-972-0006

Email: martin@bmtpatent.com, colabella@bmtpatent.com

Correspondent Name: BUCKLEY, MASCHOFF & TALWALKAR LLC

Address Line 1: 50 LOCUST AVENUE

Address Line 4: NEW CANAAN, CONNECTICUT 06840

ATTORNEY DOCKET NUMBER:	J02.004
NAME OF SUBMITTER:	NANDU A. TALWALKAR
SIGNATURE:	/NAT/
DATE SIGNED:	09/27/2019
Total Attachments: 3 source=J02.004_Executed Assignment#page1.tif source=J02.004_Executed Assignment#page2.tif source=J02.004_Executed Assignment#page3.tif	

ASSIGNMENT OF RIGHTS, TITLE AND INTEREST IN INVENTIONThis is an Assignment of the following rights, title and interest: *(check all that apply)*

- ☒ United States of America rights, title and interest in the invention
- ☒ Foreign rights, title and interest in the invention
- ☒ The following United States Patent Application
 United States Patent Application No.: 15/565,976
 which was filed on: October 12, 2017
- ☐ United States Provisional Patent Application Serial No.:
- ☐ United States Patent No(s).:
- ☒ International (PCT) Patent Application Serial No.: PCT/JP2016/057986
- ☒ Other (*specify*): JP Application No. 2015-084467 -- filed 16 April, 2015

TITLE OF THE INVENTION:

**METHOD OF PRODUCING ETCHING MASK, ETCHING MASK
 PRECURSOR, AND OXIDE LAYER, AND METHOD OF
 MANUFACTURING THIN FILM TRANSISTOR**

Inventors (assignors)

Name	Address
Satoshi INOUE	4-3-5, Mitsuinomori Karamatsudaira, 10143-9, Toyohira, Chino-shi, Nagano 391-0213 Japan
Tatsuya SHIMODA	c/o Japan Advanced Institute of Science and Technology, 1-1, Asahidai, Nomi-shi, Ishikawa 923-1292 Japan
Kazuhiro FUKADA	#206 Flora, 6-8-26, Saijyochuo, Higashihiroshima-shi, Hiroshima 739-0025 Japan
Kiyoshi NISHIOKA	c/o Sumitomo Seika Chemicals Co., Ltd. 1, Irifune-cho, Shikama-ku, Himeji-shi, Hyogo 672-8076 Japan
Nobutaka FUJIMOTO	c/o Sumitomo Seika Chemicals Co., Ltd., 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka 541-0041 Japan
Masahiro SUZUKI	c/o Sumitomo Seika Chemicals Co., Ltd. 1, Irifune-cho, Shikama-ku, Himeji-shi, Hyogo 672-8076 Japan

Assignees

Name	Address
JAPAN ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY	1-1, Asahidai, Nomi-shi, Ishikawa 923-1292 Japan
SUMITOMO SEIKA CHEMICALS CO., LTD.	346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified assignees;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignees;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignees, as assignees of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters

Patent which may be granted for my aforesaid Invention, as the Assignees or its Designee(s) may from time to time require and prepare at its own expense.

Inventors' Signatures

Sep. 8, 2017

Date

Satoshi Inoue

Satoshi INOUE

Sep 6, 2017

Date

Tatsuya Shimoda

Tatsuya SHIMODA

Sep 19, 2017

Date

Kazuhiko Fukada

Kazuhiko FUKADA

9/6/2017

Date

Kiyoshi Nishioka

Kiyoshi NISHIOKA

9/14/2017

Date

Nobutaka Fujimoto

Nobutaka FUJIMOTO

9/6/2017

Date

Masahiro Suzuki

Masahiro SUZUKI